

AMENDMENTS TO THE CLAIMS:

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1. (currently amended) An end use device having a [A] known good die (KGD) having optional solder ball array or wire bond connections;

solder ball array connections on the known good die surface;

an array of wire bond connections on the die electrically connected to the solder ball array connections;

wherein the known good die is tested [testing is completed] prior to mounting the known good die on the [an] end use device by [connecting] a test device connected to the known good die by wire bond connections or by solder ball connections;

wherein when either the wire bond connections are used or the solder ball connections are used for the known good die test [testing], the other connections are connected to the [is available for connection to an] end use device; and

the connections used for the known good die test are not connected to the end use device when the known good die is placed in the end use device.

2. (currently amended) The end use device [known good die] in accordance with claim 1, wherein when either the wire bond connections or stress tolerant solder ball connections is used to form [a] contact with the test device, the other is not affected by a known good die (KGD) test and remains pristine until connected to the end use device.

3. (currently amended) The end use device [known good di ] in accordance with claim 1, wherein the wire bond connections and the solder ball array connections are on the same side of the die.

4. (currently amended) The end use device [known good die] in accordance with claim 1, wherein the solder ball array connections and the wire bond connections are on the substantially the same level of the die [integrated circuit] so that either may provide contact with the [an] end use device.

5. (currently amended) The end use device [known good die] in accordance with claim 1, wherein the solder ball array connections or wire bond connections which are used when the die is tested [for testing] are not removed from the die [after testing].

6. (currently amended) The end use device [known good die] in accordance with claim 1, wherein connections to the test device are metallurgical connections.

7. (currently amended) The end use device [known good die] in accordance with claim 1, wherein the solder ball array connections are controlled collapse chip connections.

8. (currently amended) The end use device [known good die] in accordance with claim 1, wherein the solder ball array forming the

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solder ball array connections is a stress tolerant solder ball  
array.

*Canceled*  
9 - 10. (canceled)

44. (canceled)

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